

Title (en)
AQUEOUS COMPOSITION FOR DEPOSITING A TIN SILVER ALLOY AND METHOD FOR ELECTROLYTICALLY DEPOSITING SUCH AN ALLOY

Title (de)
WÄSSRIGE ZUSAMMENSETZUNG ZUR ABSCHIEDUNG EINER ZINN-SILBER-LEGIERUNG UND VERFAHREN ZUR ELEKTROLYTISCHEN
ABSCHIEDUNG SOLCH EINER LEGIERUNG

Title (fr)
COMPOSITION AQUEUSE POUR LE DÉPÔT D'UN ALLIAGE D'ARGENT ET D'ÉTAIN ET PROCÉDÉ DE DÉPÔT ÉLECTROLYTIQUE D'UN TEL
ALLIAGE

Publication
EP 3578693 A1 20191211 (EN)

Application
EP 18176788 A 20180608

Priority
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Abstract (en)
The present invention refers to aqueous composition for depositing a tin silver alloy, the composition comprising (a) tin ions, (b) silver ions, (c) at least one first compound independently selected from the group consisting of unsubstituted bis(aminophenyl)disulfides, substituted bis(aminophenyl)disulfides, unsubstituted dipyridyldisulfides, and substituted dipyridyldisulfides, (d) at least one second compound of formula (II) and salts thereof, wherein independently X denotes a C1 to C10 alkyl moiety comprising one or more than one sulfhydryl group, R¹ denotes hydrogen, methyl, ethyl, linear C3 to C5 alkyl, branched C3 to C5 alkyl, unsubstituted phenyl, substituted phenyl, unsubstituted benzyl, or substituted benzyl, and R² denotes methyl, ethyl, linear C3 to C5 alkyl, branched C3 to C5 alkyl, unsubstituted phenyl, substituted phenyl, unsubstituted benzyl, or substituted benzyl.

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Citation (applicant)
• JP 2006265573 A 20061005 - ISHIHARA CHEMICAL CO LTD, et al
• EP 0854206 B1 20010816 - DISPOL CHEMICALS CO LTD [JP]
• US 2014251818 A1 20140911 - OKADA HIROKI [JP], et al
• WO 03046260 A2 20030605 - SIEMENS AG [DE], et al

Citation (search report)
• [A] EP 1553211 A1 20050713 - SHINRYO ELECTRONICS CO LTD [JP]
• [A] US 6607653 B1 20030819 - TSUJI KIYOTAKA [JP], et al
• [A] EP 2221396 A1 20100825 - ROHM & HAAS ELECT MAT [US]

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